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[Vishay/Siliconix](#)
[SI4196DY-T1-E3](#)

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Si4196DY
Vishay Siliconix

N-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY

V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^{a, e}	Q _g (Typ.)
20	0.027 at V _{GS} = 4.5 V	8	8.3 nC
	0.032 at V _{GS} = 2.5 V	8	
	0.040 at V _{GS} = 1.8 V	8	

FEATURES

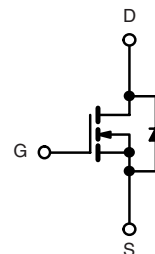
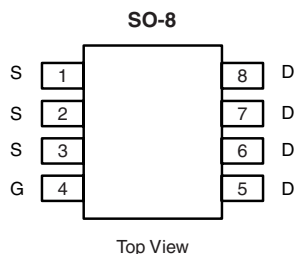
- TrenchFET® Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC



RoHS
COMPLIANT

APPLICATIONS

- DC/DC Converter
- Load Switches



Ordering Information: Si4196DY-T1-E3 (Lead (Pb)-free)

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T_A = 25 °C, unless otherwise noted

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	± 8	
Continuous Drain Current (T _J = 150 °C)	I _D	8 ^e	A
		8 ^e	
		6.4 ^{b, c}	
		5.1 ^{b, c}	
Pulsed Drain Current	I _{DM}	20	A
Continuous Source-Drain Diode Current	I _S	3.8	
		1.6 ^{b, c}	mJ
Single Pulse Avalanche Current	I _{AS}	5	
Avalanche Energy	E _{AS}	1.25	W
Maximum Power Dissipation	P _D	4.6	
		2.9	
		2.0 ^{b, c}	
		1.28 ^{b, c}	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, d}	R _{thJA}	52	62.5	°C/W
Maximum Junction-to-Foot (Drain)	R _{thJF}	22	27	

Notes:

a. Based on T_C = 25 °C.

b. Surface Mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under Steady State conditions is 110 °C/W.

e. Package limited.

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SPECIFICATIONS $T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}$, $I_D = 250\text{ }\mu\text{A}$	20			V	
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = 250\text{ }\mu\text{A}$		21		mV/ $^{\circ}\text{C}$	
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			- 3.0			
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$	0.4		1.0	V	
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 8\text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20\text{ V}$, $V_{GS} = 0\text{ V}$			1	μA	
		$V_{DS} = 20\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 55\text{ }^{\circ}\text{C}$			10		
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} \geq 5\text{ V}$, $V_{GS} = 4.5\text{ V}$	10			A	
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = 4.5\text{ V}$, $I_D = 8\text{ A}$		0.021	0.027	Ω	
		$V_{GS} = 2.5\text{ V}$, $I_D = 5\text{ A}$		0.025	0.032		
		$V_{GS} = 1.8\text{ V}$, $I_D = 2.5\text{ A}$		0.031	0.040		
Forward Transconductance ^a	g_{fs}	$V_{DS} = 10\text{ V}$, $I_D = 8\text{ A}$		28		S	
Dynamic ^b							
Input Capacitance	C_{iss}	$V_{DS} = 10\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1\text{ MHz}$		830		pF	
Output Capacitance	C_{oss}			115			
Reverse Transfer Capacitance	C_{rss}			63			
Total Gate Charge	Q_g	$V_{DS} = 10\text{ V}$, $V_{GS} = 8\text{ V}$, $I_D = 8\text{ A}$		14.5	22	nC	
Gate-Source Charge	Q_{gs}	$V_{DS} = 10\text{ V}$, $V_{GS} = 4.5\text{ V}$, $I_D = 8\text{ A}$		8.3	12.5		
Gate-Drain Charge	Q_{gd}			1.1			
Gate Resistance	R_g						
Turn-On Delay Time	$t_{d(on)}$	$f = 1\text{ MHz}$	0.6	3.0	6.0	Ω	
Rise Time	t_r		$V_{DD} = 10\text{ V}$, $R_L = 2\text{ }\Omega$ $I_D \cong 5\text{ A}$, $V_{GEN} = 4.5\text{ V}$, $R_g = 1\text{ }\Omega$		8	16	ns
Turn-Off Delay Time	$t_{d(off)}$				13	25	
Fall Time	t_f				33	60	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 10\text{ V}$, $R_L = 2\text{ }\Omega$ $I_D \cong 5\text{ A}$, $V_{GEN} = 8\text{ V}$, $R_g = 1\text{ }\Omega$			5	10	
Rise Time	t_r			9	18		
Turn-Off Delay Time	$t_{d(off)}$			12	24		
Fall Time	t_f			22	40		
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I_S	$T_C = 25\text{ }^{\circ}\text{C}$			3.8	A	
Pulse Diode Forward Current ^a	I_{SM}				20		
Body Diode Voltage	V_{SD}	$I_S = 5.4\text{ A}$		0.78	1.2	V	
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 5.4\text{ A}$, $dI/dt = 100\text{ A}/\mu\text{s}$, $T_J = 25\text{ }^{\circ}\text{C}$		11	22	ns	
Body Diode Reverse Recovery Charge	Q_{rr}			4	8	nC	
Reverse Recovery Fall Time	t_a			6		ns	
Reverse Recovery Rise Time	t_b			5			

Notes:

a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

b. Guaranteed by design, not subject to production testing.

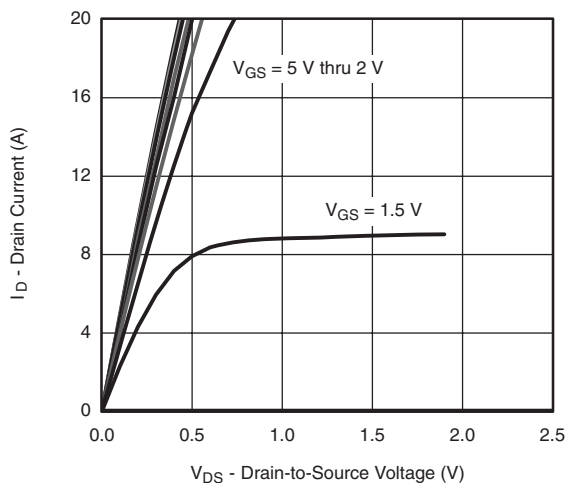
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



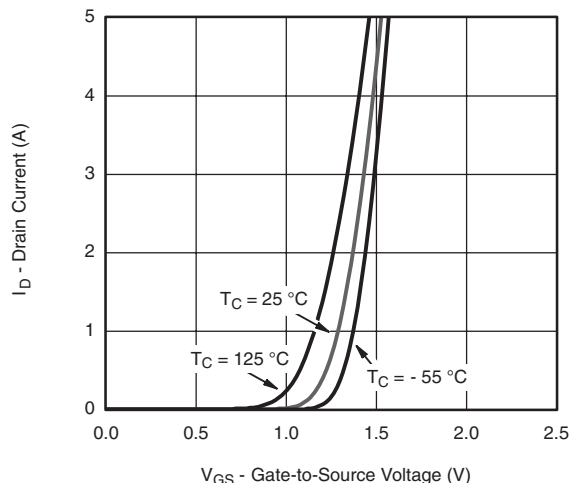
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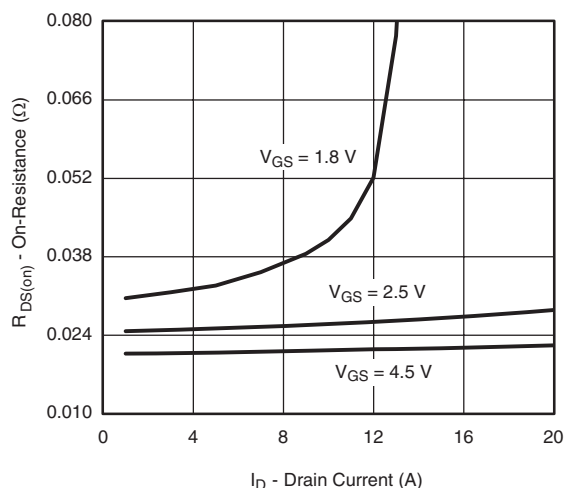
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



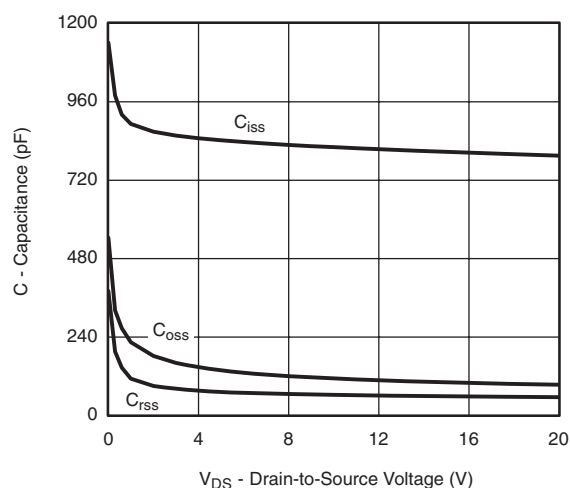
Output Characteristics



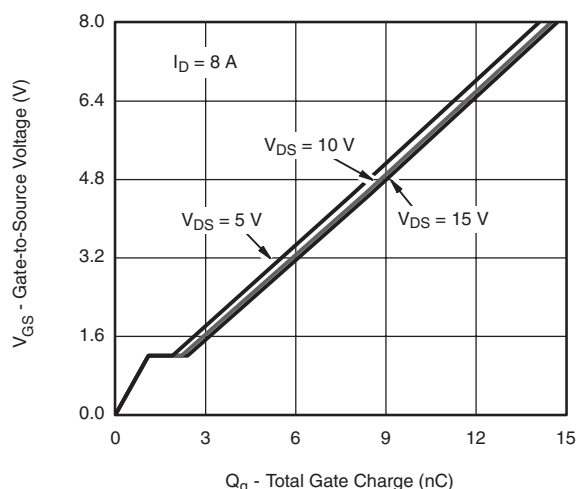
Transfer Characteristics



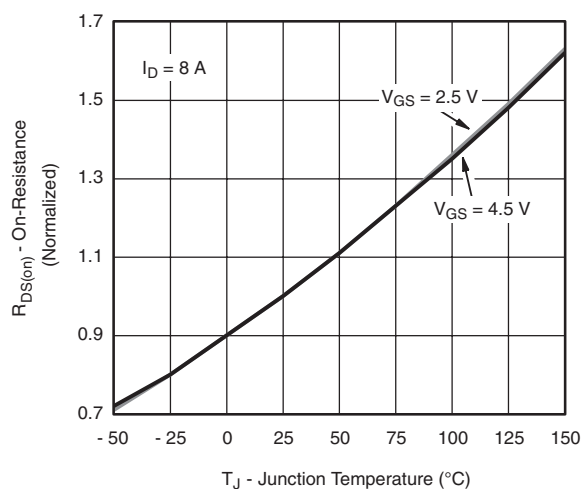
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



Gate Charge



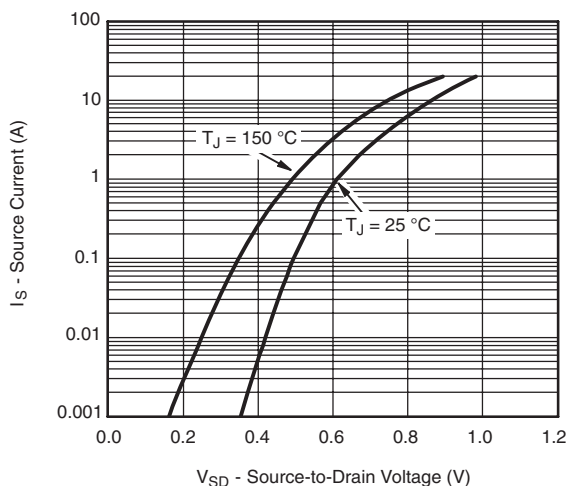
On-Resistance vs. Junction Temperature

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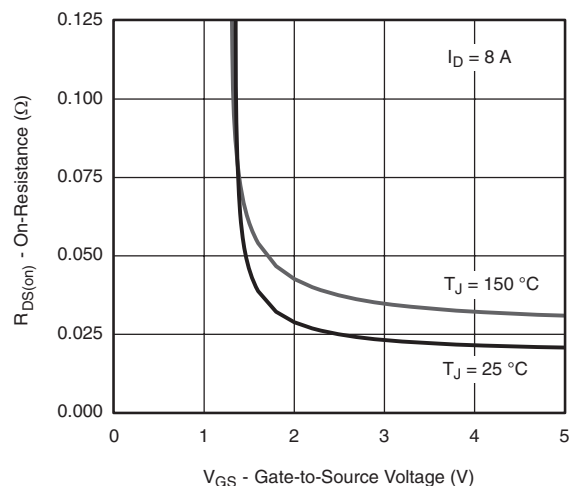
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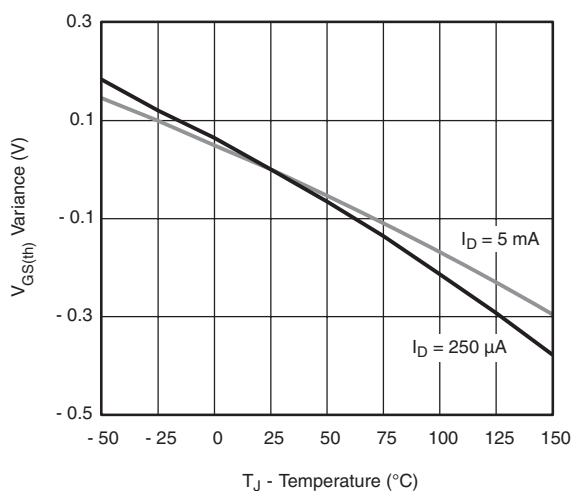
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



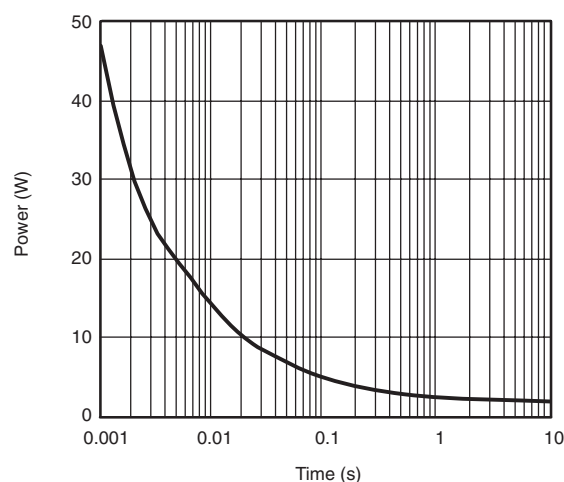
Source-Drain Diode Forward Voltage



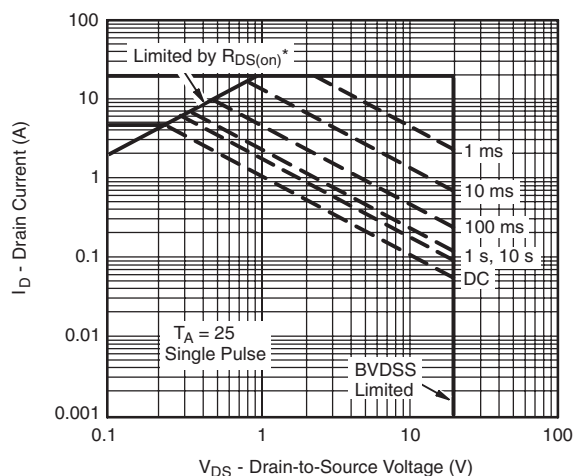
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient



* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

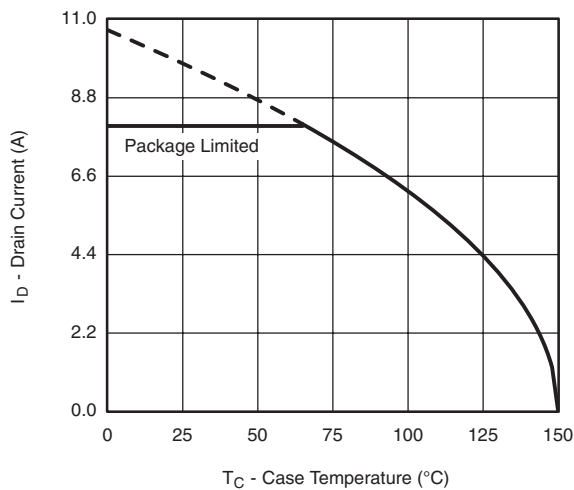
Safe Operating Area, Junction-to-Ambient



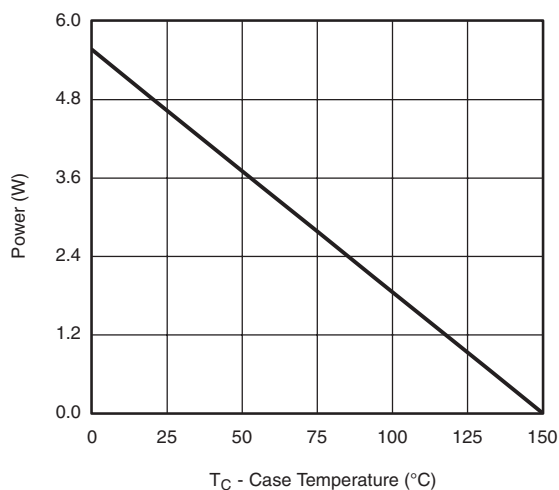
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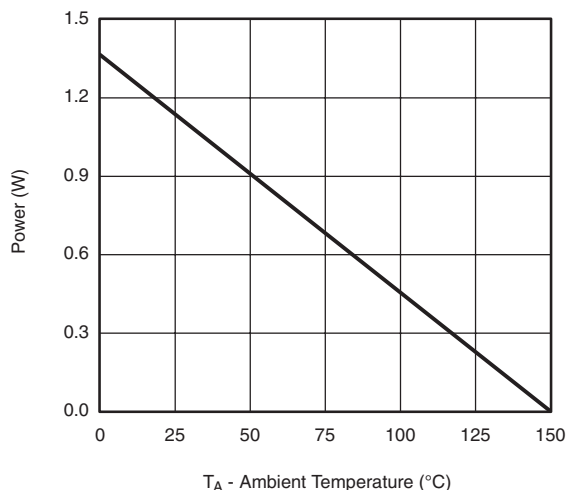
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*



Power, Junction-to-Foot



Power, Junction-to-Ambient

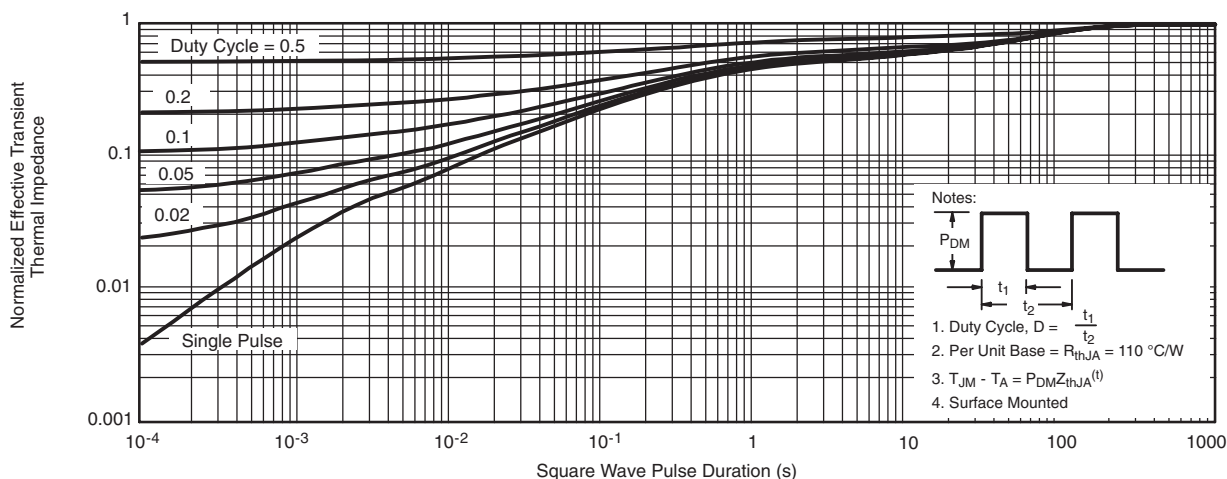
* The power dissipation P_D is based on $T_{J(max)} = 150\text{ °C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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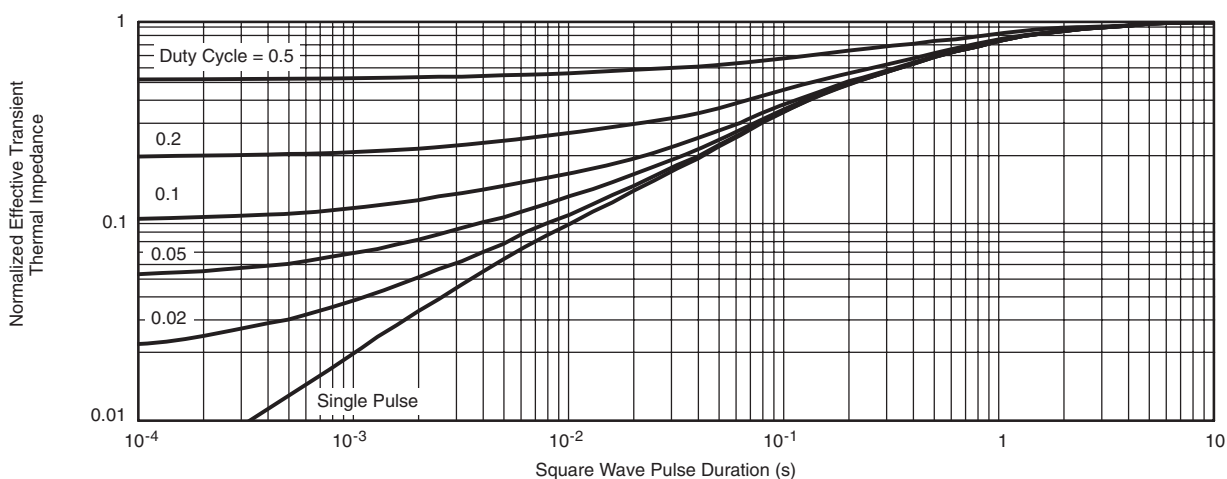
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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